

HIGH DENSITY PLANE MUTUALLY CONNECTED INTEGRATED CIRCUIT PACKAGE

Patent number: JP60049656

Publication date: 1985-03-18

Inventor: ROBAATO BAPUKA; JIYON ROORENSU PIICHIYOTA;
REONAADO JIYON POCHI

Applicant: IBM

Classification:

- **international:** H01L23/32

- **european:**

Application number: JP19840096707 19840516

Priority number(s): US19830526190 19830825

Also published as:

EP0147519 (A1)

US4553192 (A1)

EP0147519 (B1)

Abstract not available for JP60049656

Abstract of correspondent: **US4553192**

An integrated circuit module to printed circuit board interconnection system wherein the board has circuit pads to which spring contacts have one of their ends soldered to the pads. The module has circuit pads on one surface thereof and a pivotal connection is provided for loading the module onto the circuit board whereby the opposite ends of the spring contacts engage the circuit pads on the module with a wiping action and are retained in engagement therewith.

